

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S3	47	("4322698" "4388131" "4583068" "4620916" "4731297" "4837659" "4862129" "4880599" "4922156" "4959631").PN. OR ("5479695").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/16 09:19
S4	981	organic NEAR1 (board pcb)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 10:21
S5	13433	helical adj coil	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 09:21
S6	6	S4 and S5	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 09:19
S7	7133	spiral adj coil	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 09:21
S8	1	S4 and S7	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 09:21
S9	819	(planar adj coil) and via	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 11:44
S10	0	S9 and S4	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 09:22
S11	1	S4 and (planar adj coil)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 09:31
S14	0	cn1375840	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 09:33
S15	6	"1375840"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 09:44

S16	139044	glass NEAR1 (substrate board pcb pwb)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 10:52
S17	60	S5 and S16	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 09:45
S18	2782	(336/200,223,232).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/16 09:52
S19	3	S16 and S18 and helical	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 09:52
S20	2665063	(via WITH conduct\$3 winding coil wire)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 09:53
S21	26083	S16 and S20	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 09:59
S22	5131	S16 SAME S20	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 09:54
S23	11	S16 SAME S20 AND S18	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 09:54
S24	28823	S16 and S20 OR S18	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 09:59
S25	42	S16 and S20 AND S18	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 10:05
S26	3140754	teflon NEAr S3 (substrate board pcb pwb)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 10:05

S27	1292	S26 and S20 AND S18	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 10:05
S28	113	S27 and helical	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 10:06
S29	854512	(glass resin teflon kepler) NEAR6 (substrate sheet layer core board pcb pwb)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 11:38
S30	1610956	(conduct\$3 wire winding coil metal) WITH (via connect\$3 interconnect\$3 bridg\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 10:58
S31	40847	S29 SAME S30	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 10:59
S32	88	S18 AND S31	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 10:59
S33	118662	(quartz alumina ferrite) NEAR6 (substrate sheet layer core board pcb pwb)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/16 11:38
S34	982	organic NEAR1 (board pcb)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 13:18
S35	463	S34 and "30"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 10:21
S36	1611409	(conduct\$3 wire winding coil metal) WITH (via connect\$3 interconnect\$3 bridg\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 10:21
S37	371	S34 and S36	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 10:28

S38	112	S34 SAME S36	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 10:27
S39	4	S38 and induct\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 10:27
S40	42	S37 and induct\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 10:41
S41	2782	(336/200,223,232).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/17 10:41
S42	2	S34 and S41	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 10:41
S43	5	("5708296" "5714801" "5898217" "6008534" "6828666").PN. OR ("6979890").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/17 10:42
S44	6068	organic NEAR5 (board pcb)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 10:43
S45	6	S41 and S44	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 10:43
S46	2	("6891461").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/17 10:48
S47	122	S34 SAME (heat\$3 anneal\$3 sinter\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 11:06
S48	187	S34 SAME (heat\$3 anneal\$3 thermal sinter\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 13:19
S49	120	S48 and (induct\$3 conduct\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 11:07

S50	2	S34 SAME cofir\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 12:40
S52	1532	(inorganic in\$1organic) NEAR1 (board pcb)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 13:28
S54	230	S52 SAME (heat\$3 anneal\$3 thermal sinter\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 13:29
S55	1	S41 and S54	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 13:20
S56	61463	(quartz alumina ferrite) NEAR1 (board core plate sheet layer substrate pcb)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 10:20
S57	16550	S56 SAME (heat\$3 cofir\$3 anneal\$3 thermal sinter\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 18:44
S58	9369	S56 WITH (heat\$3 cofir\$3 anneal\$3 thermal sinter\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 13:30
S59	57	S41 and S58	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 14:01
S60	105	S41 and S57	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 14:08
S61	2	("4803543").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/17 14:01
S62	4	("6737012").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/17 15:02

S63	297	((("5406119") or ("5561325") or ("5633479") or ("6198376") or ("5611014") or ("5281770") or ("6219912") or ("6219912") or ("6324068") or ("6316738") or ("6342682") or ("6256170") or ("5626152") or ("4889749") or ("5953784") or ("6065518") or ("6118069") or ("6248412") or ("6462356") or ("4619428") or ("5285106") or ("5636099") or ("6002494") or ("6043980") or ("6172872") or ("5530415") or ("5757251") or ("6400527") or ("6365438") or ("5017341") or ("5635742") or ("5671165") or ("6211606") or ("6211606") or ("5561010") or ("5894389") or ("5935741") or ("6080515") or ("5214495") or ("5229555") or ("5668390") or ("5821133") or ("6189204") or ("6233034") or ("6242995") or ("5801447") or ("4802276") or ("5214289") or ("5299955") or ("5316894") or ("5391894") or ("5516715") or ("5976972") or ("6053746") or ("6163067") or ("5576518") or ("3577633") or ("3796019") or ("4872544") or ("4988404") or ("5275521") or ("5473188") or ("5640033") or ("5647792") or ("5721148") or ("5726098") or ("5818551") or ("6064456") or ("6635926") or ("5743630") or ("5985725") or ("5838061") or ("6184145") or ("5544773") or ("5719426") or ("5972540") or ("6410973") or ("6465085") or ("6437299") or ("6077757") or ("4457803") or ("4595452") or ("4465705") or ("5437947") or ("5679499") or ("5882534") or ("5891749") or ("5914204") or ("6069060") or ("6087246") or ("6090695") or ("6093641") or ("6117757") or ("6168907") or ("6180516") or ("6210842") or ("6210842") or ("5243308") or ("5321373") or ("5889325") or ("6165866") or ("5592024") or ("6060346") or ("6090699") or ("6146960") or ("6794286") or ("6232161") or ("5613995") or ("5445526") or ("5598757") or ("5831361") or ("6301111") or ("4800455") or ("5875047") or ("5200727") or ("5220491") or ("4277802") or ("4814920") or ("5316878") or ("5434895") or ("6313895") or ("5321786") or ("6282350") or ("6282775") or ("6312364") or ("6371664") or ("4295906") or ("4888568") or ("4891577") or ("5189638") or ("4951240") or ("5319271") or ("5747908") or ("6459592") or ("4955753") or ("5233319") or ("5250794") or ("5899908") or ("3661166") or ("4091691") or ("4251854") or ("4257204") or ("4264251") or ("4285838") or ("4297819") or ("4329027") or ("4336791") or ("4347412") or ("4365791") or ("4390390"))).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/17 15:03
S64	2782	(336/200,223,232).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/17 18:44
S65	61463	(quartz alumina ferrite) NEAR1 (board core plate sheet layer substrate pcb)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 18:44

S66	16550	S65 SAME (heat\$3 cofir\$3 anneal\$3 thermal sinter\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 18:44
S67	105	S66 and S64	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 18:44
S68	160	teflon WITH silica WITH substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 20:00
S69	2782	(336/200,223,232).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/17 19:59
S70	27621	"336"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 20:00
S71	26	S68 and induct\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/17 20:37
S72	4	("2002010327").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/18 07:35
S73	2	("20020103270").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/18 09:11
S74	2	("6489875").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/18 09:21
S75	3	("6713162").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/18 09:21
S77	2	("3992691").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/18 09:32

S78	5765	organic WITH filler WITH (substrate board sheet layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 10:07
S79	663	S78 SAME (inductor conduct\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 10:07
S80	513	S78 WITH (inductor conduct\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 10:04
S81	1715	organic WITH filler WITH (substrate board)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 10:07
S82	273	S81 SAME (inductor conduct\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 10:07
S83	495	(quartz alumina ferrite) NEAR1 (sintered) WITH (substrate pcb board)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 10:25
S84	2	("6864774").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/18 10:37
S88	1813	(336/200).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/18 10:38
S89	19	S88 and (ahn adj kie)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 11:43
S90	3892	(29/602.1,606).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/18 15:08
S91	819	(planar adj coil) and via	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 11:46

S92	11	S90 and S91	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 11:44
S93	129	S90 and (conductor WITH via)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 13:43
S94	3	("6713162").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/18 13:45
S95	1	"09852794"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 14:05
S96	2	("20020009577").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/18 14:06
S97	8230	(teflon keplar resin organic) WITH (filler silica) WITH substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 15:55
S98	3862	S97 and (conduct\$3 inductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 15:56
S99	897	S97 WITH (conduct\$3 inductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 15:12
S10 1	2782	(336/200,223,232).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/18 15:09
S10 5	29	S97 WITH (conduct\$3 inductor) and transformer	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 15:13
S10 6	122	S97 and transformer	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 15:13

S10 7	1984	(epoxy polyimide) WITH (filler silica) WITH substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 15:55
S10 8	1129	S107 and (conduct\$3 inductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 15:56
S10 9	411	S107 same (conduct\$3 inductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/18 15:56